

SLOS609-DECEMBER 2008

www.ti.com

QUAD PRECISION OPERATIONAL AMPLIFIER

FEATURES

- Single-Supply Operation: Input Voltage Range Extends to Ground, and Output Swings to Ground While Sinking Current
- Input Offset Voltage 300 mV Max at 25°C
- Offset Voltage Temperature Coefficient 2.5 μV/°C Max
- Input Offset Current 1.5 nA Max at 25°C
- High Gain 1.2 V/μV Min (R_L = 2 kΩ), 0.5 V/μV Min (R_L = 600 Ω)
- Low Supply Current 2.2 mA Max at 25°C
- Low Peak-to-Peak Noise Voltage 0.55 μV Typ
- Low Current Noise 0.07 pA/\/Hz Typ

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Military (-55°C/125°C) Temperature Range⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability

DW PACKAGE (TOP VIEW)							
10UT [1	16] 4OUT				
1IN- [2	15] 4IN-				
1IN+ [3	14] 4IN+				
V _{CC+} [4	13] V _{CC-} /GND				
2IN+ [5	12] 3IN+				
2IN- [6	11] 3IN-				
2OUT [7	10] 3OUT				
NC [8	9] NC				
	1						

(1) Additional temperature ranges are available - contact factory

DESCRIPTION

The LT1014D is a quad precision operational amplifier with 14-pin industry-standard configuration. It features low offset-voltage temperature coefficient, high gain, low supply current, and low noise.

The LT1014D can be operated with both dual \pm 15-V and single 5-V power supplies. The common-mode input voltage range includes ground, and the output voltage can also swing to within a few milivolts of ground. Crossover distortion is eliminated.

ORDERING INFORMATION⁽¹⁾

T _A	PAC	KAGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SIOC-DW	Reel of 2000	LT1014DMDWREP	LT1014DMEP

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SLOS609-DECEMBER 2008



www.ti.com







www.ti.com

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	supply voltage ⁽²⁾		-22	2 22	V
	Differential input voltage ⁽³⁾		-30) 30	V
VI	Input voltage range (any input) ⁽²⁾		V _{CC-} - 5	5 V _{CC+}	V
	Duration of short-circuit current ⁽⁴⁾	T _A ≤ 25°C		Unlimited	
	Continuous total power dissipation		See Diss	ipation Rating	s Table
T _A	Operating temperature range		-5	5 125	°C
T _{stg}	Storage temperature range		-6	5 150	°C
	Lead temperature 1,6 mm, at distance 1/16 inch from case for	r 10s		260	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.

(3) Differential voltages are at the noninverting input with respect to the inverting input.

(4) The output may be shorted to either supply.

DISSIPATION RATINGS

PACKAGE	T _A ≤ 25°c POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 105°C POWER RATING	T _A = 125℃ POWER RATING
DW	1025 mV	8.2 mW/°C	656 mW	369 mW	205 mW

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range, V_{CC+} = 5 V, V_{CC-} = 0, V_O = 1.4 V, V_{IC} = 0 (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T _A ⁽¹⁾	MIN	ТҮР	MAX	UNIT
		R - 50 0	25°C		90	450	
V _{IO}	Input offset voltage	$R_{\rm S} = 50.02$	Full range		400	1500	μV
		$R_S = 50 \ \Omega, \ V_{IC} = 0.1 \ V$	125°C		200	750	
1	Input offect current		25°C		0.2	2	n۸
10	input onset current		Full range			10	ΠA
1	Input bios current		25°C		-15	-50	n۸
чв	Input bias current		Full range			-120	ПА
V	Common-mode input voltage		25°C	0 to 3.5	-0.3 to 3.8		V
VICR	range		Full range	0.1 to 3			v
		Output low, no load	25°C		15	25	
		Quput low, P 600 Q to GND	25°C		5	10	mV
		$Cuput low, R = 000 \Omega to GRD$	Full range			18	
V _{OM}	Maximum peak output voltage swing	Output low, I _{SINK} = 1 mA	25°C		220	350	
	renage ennig	Output high, no load	25°C	4	4.4		
		Output high	25°C	3.4	4		V
		$R_L = 600 \Omega$ to GND	Full range	3.1			
A_{VD}	Large-signal differential voltage amplification	V_{O} = 5 mV to 4 V, R_{L} = 500 Ω	25°C		1		V/μV
1	Supply current per amplifier		25°C		0.3	0.5	m۵
'CC	Supply current per ampliner		Full range			0.65	ШA

(1) Full range is -55°C to 125°C.

Texas Instruments

www.ti.com

SLOS609-DECEMBER 2008

OPERATING CHARACTERISTICS

over operating free-air temperature range, $V_{CC\pm}$ = 15 V, V_{IC} = 0, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Slew rate		0.2	0.4		V/µs
V	Equivalant input poice valtage	f = 10 Hz		24		n)////Цन
vn	Equivalent input hoise voitage	f = 1kHz		22		
V _{N(PP)}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 10 Hz		0.55		μV
l _n	Equivalent input noise current	f = 10 Hz		0.07		pA/√Hz

TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE		
V _{IO}	Input offset voltage vs balanced sour	rce resistance	Figure 2		
V _{IO}	Input offset voltage vs free-air tempe	erature	Figure 3		
ΔV_{IO}	Warm-up change in input offset volta	Figure 4			
I _{IO}	Input offset current vs Input offset cu	irrent vs free-air temperature	Figure 5		
I _{IB}	Input bias current vs free-air tempera	ature	Figure 6		
V _{IC}	Common-mode input voltage vs inpu	it bias current	Figure 7		
•		vs load resistance	Figure 8 Figure 9		
A _{VD}	Differential voltage amplification	vs frequency	Figure 10 Figure 11		
	Channel separation vs frequency	Figure 12			
	Output saturation voltage vs free-air	temperature	Figure 13		
CMRR	Common-mode rejection ratio vs free	quency	Figure 14		
k _{SVR}	Supply-voltage rejection ratio vs freq	uency	Figure 15		
I _{CC}	Supply current vs free-air temperatur	re	Figure 16		
I _{OS}	Short-circuit output current vs elapse	ed time	Figure 17		
V _n	Equivalent input noise voltage vs free	quency	Figure 18		
I _n	Equivalent input noise current vs free	Equivalent input noise current vs frequency			
V _{N(PP)}	Peak-to-peak input noise voltage vs	Figure 19			
	Pulse response (small signal) vs time	e	Figure 20 Figure 22		
	Pulse response (large signal) vs time	9	Figure 21 Figure 23 Figure 24		
	Phase shift vs frequency	Figure 10			



SLOS609-DECEMBER 2008





www.ti.com

SLOS609-DECEMBER 2008





SLOS609-DECEMBER 2008







CMRR - Common-Mode Rejection Ratio - dB

 I_{CC} - Suppl y Current Per Amplifier - μV

Texas INSTRUMENTS

www.ti.com





SLOS609-DECEMBER 2008





www.ti.com

SLOS609-DECEMBER 2008





SLOS609-DECEMBER 2008

www.ti.com

APPLICATION INFORMATION

SINGLE-SUPPLY OPERATION

The LT1014D is fully specified for single-supply operation (V_{CC} = 0). The common-mode input voltage range includes ground, and the output swings within a few millivolts of ground.

Furthermore, the LT1014D has specific circuitry that addresses the difficulties of single-supply operation, both at the input and at the output. At the input, the driving signal can fall below 0 V, either inadvertently or on a transient basis. If the input is more than a few hundred millivolts below ground, the LT1014D is designed to deal with the following two problems that can occur:

- 1. On many other operational amplifiers, when the input is more than a diode drop below ground, unlimited current flows from the substrate (V_{CC} terminal) to the input, which can destroy the unit. On the LT1014D, the 400- Ω resistors in series with the input (see schematic) protect the device even when the input is 5 V below ground.
- 2. When the input is more than 400 mV below ground (at T_A = 25°C), the input stage of similar type operational amplifiers saturates, and phase reversal occurs at the output. This can cause lockup in servo systems. Because of unique phase-reversal protection circuitry (Q21, Q22, Q27, and Q28), the LT1014D outputs do not reverse, even when the inputs are at -1.5 V (see Figure 25).

However, this phase-reversal protection circuitry does not function when the other operational amplifier on the LT1014D is driven hard into negative saturation at the output. Phase-reversal protection does not work on an amplifier:

- When 4's output is in negative saturation (the outputs of 2 and 3 have no effect)
- When 3's output is in negative saturation (the outputs of 1 and 4 have no effect)
- When 2's output is in negative saturation (the outputs of 1 and 4 have no effect)
- When 1's output is in negative saturation (the outputs of 2 and 3 have no effect)

At the output, other single-supply designs either cannot swing to within 600 mV of ground or cannot sink more than a few microproamperes while swinging to ground. The all-npn output stage of the LT1014D maintains its low output resistance and high gain characteristics until the output is saturated. In dual-supply operations, the output stage is free of crossover distortion.



Figure 25. Voltage-Follower Response With Input Exceeding the Negative Common-Mode Input Voltage Range

Texas Instruments

www.ti.com

SLOS609-DECEMBER 2008

COMPARATOR APPLICATIONS

The single-supply operation of the LT1014D can be used as a precision comparator with TTL-compatible output. In systems using both operational amplifiers and comparators, the LT1014D can perform multiple duties (see Figure 26 and Figure 27).



for Various Input Overdrives



LOW-SUPPLY OPERATION

The minimum supply voltage for proper operation of the LT1014D is 3.4 V (three Ni-Cad batteries). Typical supply current at this voltage is 290 μ A; therefore, power dissipation is only 1 mW per amplifier.

OFFSET VOLTAGE AND NOISE TESTING

Figure 31 shows the test circuit for measuring input offset voltage and its temperature coefficient. This circuit with supply voltages increased to ±20 V is also used as the burn-in configuration.

The peak-to-peak equivalent input noise voltage of the LT1014D is measured using the test circuit shown in Figure 28. The frequency response of the noise tester indicates that the 0.1-Hz corner is defined by only one zero. The test time to measure 0.1-Hz to 10-Hz noise should not exceed 10 seconds, as this time limit acts as an additional zero to eliminate noise contribution from the frequency band below 0.1 Hz.

An input noise-voltage test is recommended when measuring the noise of a large number of units. A 10-Hz input noise-voltage measurement correlates well with a 0.1-Hz peak-to-peak noise reading because both results are determined by the white noise and the location of the 1/f corner frequency.

Noise current is measured by the circuit and formula shown in Figure 29. The noise of the source resistors is subtracted.



www.ti.com

LT1014D-EP

SLOS609-DECEMBER 2008



NOTE A: All capacitor values are for nonpolarized capacitors only.





[†] Metal-film resistor







Figure 30. Test Circuit for V_IO and αV_{IO}

SLOS609-DECEMBER 2008



[†] 1% film resistor. Match 10-k Ω resistors 0.05%. [‡] T1 = PICO-31080

Figure 31. 5-V Powered, 4-mA to 20-mA Current-Loop Transmitter With 12-Bit Accuracy

Texas

INSTRUMENTS



SLOS609-DECEMBER 2008



Figure 32. Fully Floating Modification to 4-mA to 20-mA Current-Loop Transmitter With 8-Bit Accuracy



NOTE A: V_{IO} = 150 μ V, A_{VD} = (R1/R2) + 1, CMRR = 120 dB, V_{ICR} = 0 to 5 V

Figure 33. 5-V Single-Supply Dual Instrumentation Amplifier



www.ti.com



 † 1% film resistor Match 10-k $_{\Omega}$ resistors 0.05%.

[‡] For high source impedances, use 2N2222 as diodes (with collector connected to base).

NOTE A: A_{VD} = (400,000/RG) + 1

Figure 34. 5-V Powered Precision Instrumentation Amplifier



31-May-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LT1014DMDWREP	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LT1014DMEP	Samples
V62/09614-01XE	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LT1014DMEP	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



PACKAGE OPTION ADDENDUM

31-May-2014

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LT1014D-EP :

Catalog: LT1014D

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LT1014DMDWREP	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LT1014DMDWREP	SOIC	DW	16	2000	367.0	367.0	38.0

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AA.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconr	nectivity	

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2014, Texas Instruments Incorporated